IN THE SPECIFICATION

Please replace paragraph [0026] with the following amended paragraph:

[0026] Apparatus and methods for the imprinting an embossable film disposed above a substrate using a workpiece handler and alignment assembly are described. By way of example only, embodiments of a workpiece handler and alignment assembly are described with respect to a disk substrate. However, it may be appreciated by one of skill in the art that embodiments of a workpiece handler and alignment assembly may be easily adapted for substrates that vary in shape and size (e.g., square, rectangular, etc.), for the production of different types of substrates discussed above. In one embodiment, the apparatus and methods described herein may be used for the fabrication of disks utilizing nano-imprinting lithography techniques. In one embodiment, a pickup head is positioned in close proximity to a horizontally presented disk substrate. Gas (e.g., air) is gradually admitted into a first port where it is distributed around an annular manifold. A turbulent gas distributor disposed near the annular manifold equalizes the gas flow/pressure exiting ~~an~~ a gas knife gap around the disk substrate. The high velocity gas flow clings to the flat underside of the pickup head by means of the Coanda effect.

Please replace paragraph [0036] with the following amended paragraph:

[0036] To center disk substrate 250 relative to embossing foil 282, actuators 242, 244, 246 ~~extends~~ extend push rods 252, 254, 256 to engage an outer diameter of disk substrate 250. It should be noted that, with respect to **FIGS. 3A – 3B**, only two actuators and push rods are shown. However, in an alternative embodiment, multiple actuators and rods may be disposed around the disk substrate (e.g., actuators 242, 244, 246 and rods 252, 254, 256 as discussed above with respect to **FIGS. 2A – 2C**). When multiple push rods are used, they engage the OD of disk substrate 250 in synchronism in the manner of

a 3-jaw chuck. The push rods may be used to center disk substrate 250 relative to a centerline of embossing foil 282, establishing a centering position for subsequent disk substrates. In one embodiment, actuators 242, 244, 246 may be ways to for achieving nano actuation. In one embodiment, actuators 242, 244, 246 may be piezo actuators. In an alternative embodiment, actuators 242, 244, 246 may be voice coil actuators. Once disk substrate 250 is centered relative to embossing foil 282, encoders coupled to actuators 242, 244, 246 may sense motion stoppage, allowing an actuator controller (not shown) to hold the position of rods 252, 254, 256 and securely clamp disk substrate 250. All gas flow from pickup head 212 may be stopped and pickup head 212 may then be withdrawn from a position above receiving nest 280. Embossing foil 282 may then be pressed into the embossing film of disk substrate 250. Subsequent disk substrates may be checked for drift from the original centering alignment, and the actuator controller may be adjusted in real-time to reposition a disk substrate. As such, the use of one or more actuators/push rods may be biased to attain an infinite number of centering positions for a disk substrate relative to an embossing foil.

IN THE DRAWINGS

The attached sheet includes a change to FIG. 6A. This sheet replaces the originally filed sheet that included FIG. 6A. FIG. 6A has been amended to correct a typographical error. It is respectfully submitted that the proposed amendment to the drawings does not add new matter. Support for this amendment may found on page 20, paragraph [0044].

Attachment: Replacement Sheet
Annotated Sheet Showing Changes